SCOPE :

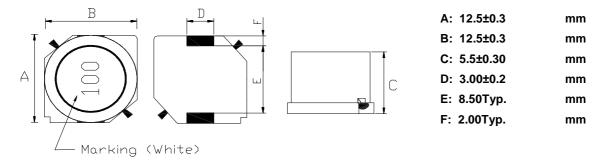
This specification applies to the Pb Free high current type SMD inductors for MSCDRI-125F-SERIES

PRODUCT INDENTIFICATION

MSCDRI-125F-100 M

- ① Product Code
- ② Dimensions Code
- ③ Inductance Code
- ④ Tolerance Code

(1) SHAPES AND DIMENSIONS



(2) ELECTRICAL SPECIFICATIONS

SEE TABLE 1

TEST INSTRUMENTS

L : HP 4284A PRECISION LCR METER (or equivalent) RDC : CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

(3) CHARACTERISTICS

- (3)-1 Ambient temperature +60°C Max.
- (3)-2 Operate temperature range $-40^\circ C \sim +125^\circ C$ (Including self temp. rise)
- (3)-3 Storage temperature range $-40^\circ\!\mathrm{C}\,{\sim}\,{+}\,125^\circ\!\mathrm{C}$



TABLE 1

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated D	C Current	Morking
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω)±20%	IDC1(A)	IDC2(A)	Marking
MSCDRI-125F-6R0	6.0	Ν	100kHz/0.5V	16.4m	3.6	4.9	6R0
MSCDRI-125F-100	10	M,N	100kHz/0.5V	21.5m	3.4	4.3	100
MSCDRI-125F-150	15	M,N	100kHz/0.5V	25.9m	2.8	3.9	150
MSCDRI-125F-220	22	M,N	100kHz/0.5V	33.8m	2.3	3.4	220
MSCDRI-125F-330	33	M,N	100kHz/0.5V	41.5m	1.9	3.1	330
MSCDRI-125F-470	47	M,N	100kHz/0.5V	61.8m	1.6	2.5	470
MSCDRI-125F-680	68	M,N	100kHz/0.5V	83.2m	1.3	2.2	680
MSCDRI-125F-101	100	K,M	100kHz/0.5V	0.117	1.1	1.8	101
MSCDRI-125F-151	150	K,M	100kHz/0.5V	0.19	0.88	1.4	151
MSCDRI-125F-221	220	K,M	100kHz/0.5V	0.27	0.72	1.2	221
MSCDRI-125F-331	330	K,M	100kHz/0.5V	0.41	0.59	1.0	331
MSCDRI-125F-471	470	K,M	100kHz/0.5V	0.52	0.49	0.88	471
MSCDRI-125F-681	680	K,M	100kHz/0.5V	0.76	0.43	0.73	681
MSCDRI-125F-102	1000	K,M	100kHz/0.5V	1.12	0.34	0.60	102
MSCDRI-125F-122	1200	K,M	100kHz/0.5V	1.48	0.32	0.53	122
MSCDRI-125F-152	1500	K,M	100kHz/0.5V	1.73	0.29	0.48	152

% □ specify the inductance tolerance,K(±10%),M(±20%),N(±30%)

% IDC1 : Based on inductance change (△L/Lo : \leq drop 10%)@ ambient temp. 25°C

IDC2 : Based on temperature rise ($\triangle T : 40^{\circ}C$ TYP.)

Rated DC Current : The less value which is IDC1 or IDC2.



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS		
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board		
		in figure 1 and a load applied unitil the figure in the arrow		
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)		
	no mechanical	PCB dimension shall the page 7/9		
	damage or elec-	F(Pressurization)		
	trical damege.	П		
		R5 45±2 45±2 1 10 20 R340 R340		
		PRESSURE ROD		
		figure-1		
Vibration	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board		
		and when a vibration having an amplitude of 1.52mm		
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should		
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.		
	damage.	(A total of 6 hours)		
Solderability	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated		
Solderability	More than 90%	over the whole of the sample before hard, the sample shall		
		then be preheated for about 2 minutes in a temperature of		
		130 \sim 150 $^\circ\!\mathrm{C}$ and after it has been immersed to a depth 0.5mm		
		below for 3±0.2 seconds fully in molten solder M705 with		
		a temperature of 245±5°C.		
		More than 90% of the electrode sections shall be couered		
		with new solder smoothly when the sample is taken out of		
		the solder bath.		



MECHANICAL

TEST ITEM	SPECIFICATION				
TEST ITEM Resistance to Soldering heat (reflow soldering)	There shall be no damage or problems.	SPECIFICATION Temperature profile of reflow soldering soldering (Peak temperature 260±3°C 10 sec yeak temperature 2			

ELECTRICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Insulation	There shall be	DC 100V voltage shall be applied across this sample of top
resistance	no other	surface and the terminal.
	damage or	The insulation resistance shall be more than $1 \times 10^8 \Omega$.
	problems.	
Dielectric	There shall be	AC 100V voltage shall be applied for 1 minute acrosset the top
withstand	no other	surface and the terminal of this sample
voltage	damage or	
	problems.	
Temperature	∆L/L20℃≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85 $^\circ\! { m C}$,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be $ riangle L/L20^\circ\!C$ \leq ±10%.



ENVIROMENT CHARACTERISTICS

TEST ITEM			SPECIFICATION				
High temperature	∆L/Lo≦±5%	\triangle L/Lo \leq ±5% The sample shall be left for 96±4 hours in an atmospere with					
storage		a temperat	a temperature of 85±2 $^\circ\!\!{ m C}$ and a normal humidity.				
	There shall be	Upon completion of the measurement shall be made after the					
	no mechanical	sample has been left in a normal temperature and normal					
	damage.	humidity fo	humidity for 1 hour.				
Low temperature		The sample shall be left for 96±4 hours in an atmosphere with					
storage		a temperat	a temperature of -25±3 $^{\circ}$ C.				
-	There shall be	Upon comp	Upon completion of the test, the measurement shall be made				
	no mechanical	after the sa	after the sample has been left in a normal temperature and				
	damage.	normal hun	normal humidity for 1 hour.				
Change of	 ∆L/Lo≦±5%	The sample	shall be subject to 5 cont	inuos cycles, such as show	/n		
emperature		in the table	2 below and then it shall b	e subjected to standard			
	There shall be	stmospher	stmospheric conditions for 1 hour, after which measurement				
	no other dama-	shall be ma	shall be made.				
	ge of problems						
			table 2				
			Temperature	Duration			
		1	−25±3° C	30 min.			
			(Themostat No.1)	50 mm.			
		2	Standard	No.1→No.2			
			atmospheric				
		3	85±2℃	30 min.			
			(Themostat No.2)	30 mm.			
		4	Standard				
			atmospheric	No.2→No.1			
Moisture storage	∆L/Lo≦±5%	The sample	shall be left for 96±4 hour	s in a temperature of			
		40±2℃ and	40±2℃ and a humidity(RH) of 90 \sim 95%.				
	There shall be	Upon completion of the test, the measurement shall be made					
	no mechanical	after the sample has been left in a normal temperature and					
	damage.	normal humidity more than 1 hour.					
Fest conditions :							
The	sample shall be reflor	w soldered on	to the printed circuit board	l in every test.			



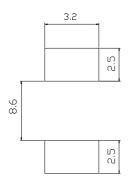
(5) LAND DIMENSION (Ref.)

PCB: GLASS EPOXY t=1.6mm

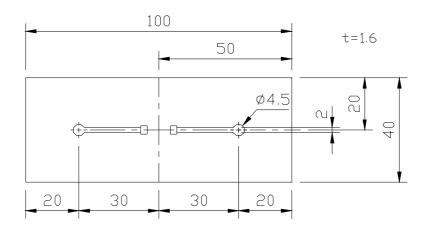
(5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN)



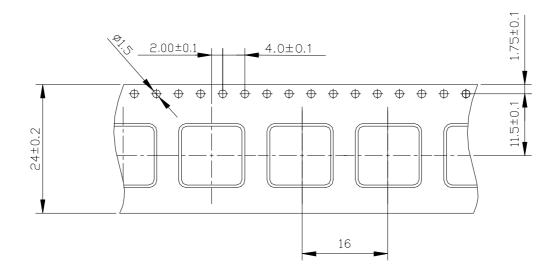


(5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD



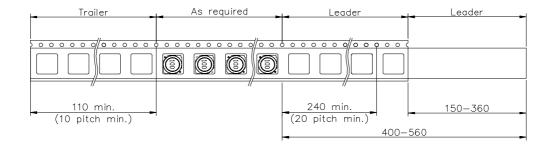


(6) PACKAGING (6)-1 CARRIER TAPE DIMENSIONS (mm)



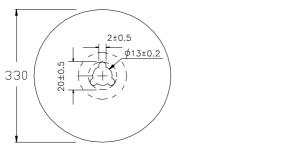
(6)-2 TAPING DIMENSIONS (mm)

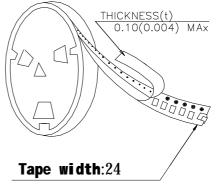






(6)-3 REEL DIMENSIONS (mm)





(6)-4 QUANTITY

500pcs/Reel

The products are packaged so that no damage will be sustained.

